Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model **[List multiple models if applicable.]**
HPE ProLiant ML350 Gen10

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		5
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Item Description	Notes	Quantity of items included in product
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screwdriver Bits	(T-10)
Description #2 Screwdriver Bits	(T-15)
Description #3 Screwdriver Bits	(T-30)
Description #4 Screwdriver Bits	Sleeve

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

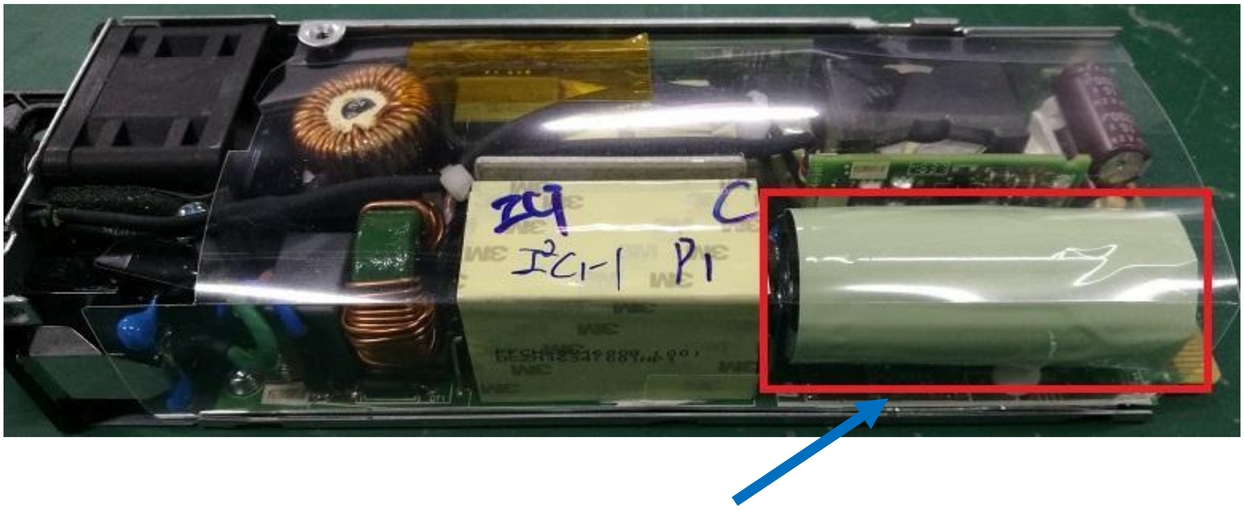
Attachment 1# : Remove Batteries

Remove Mega Cell module from chassis

Attachment 2# : HSTNS-PD60

Remove capacitor

Attachment 3# : HSTNS-PD44



Remove capacitor

Attachment 4# : HSTNS-PL45

Remove capacitor

Attachment 5# : HSTNS-PC40

Remove capacitor

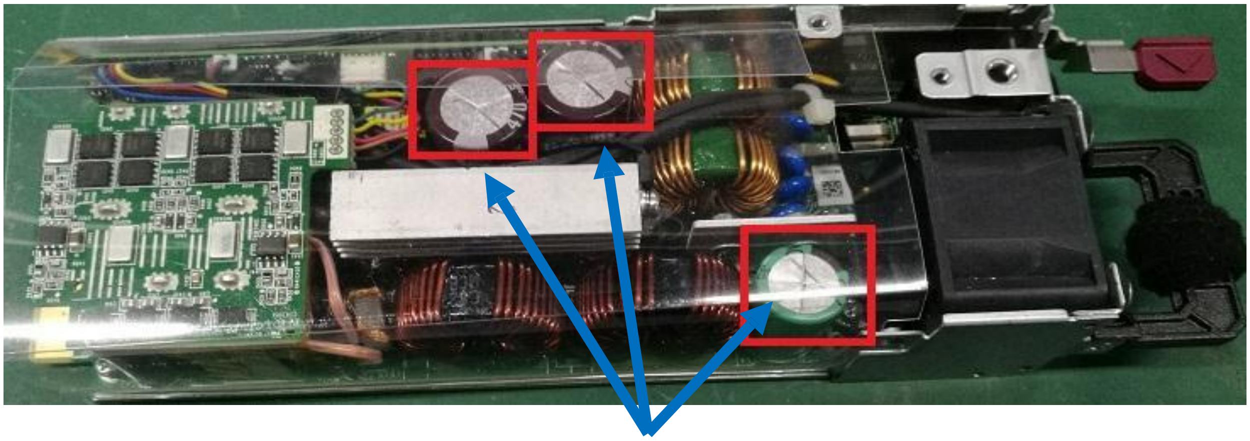
Attachment 6# : HSTNS-PL40

Remove capacitor

Attachment 7# : HSTNS-PD40

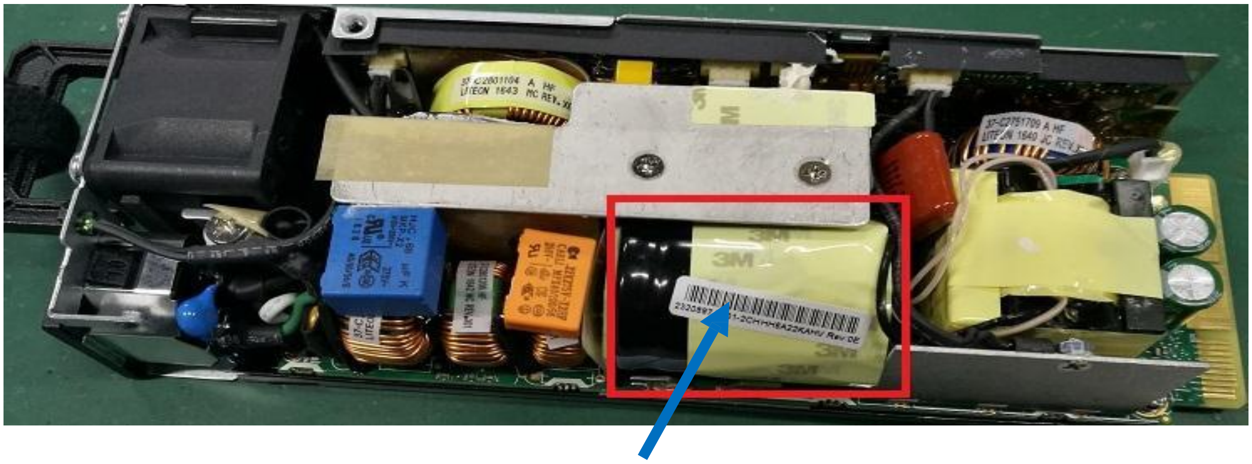
Remove capacitor

Attachment 8# : HSTNS-PF46



Remove capacitor

Attachment 9# : HSTNS-PL41



Remove capacitor

Attachment 10# : HSTNS-PC41

Remove capacitor

Attachment 11# : HSTNS-PR62

Remove capacitor

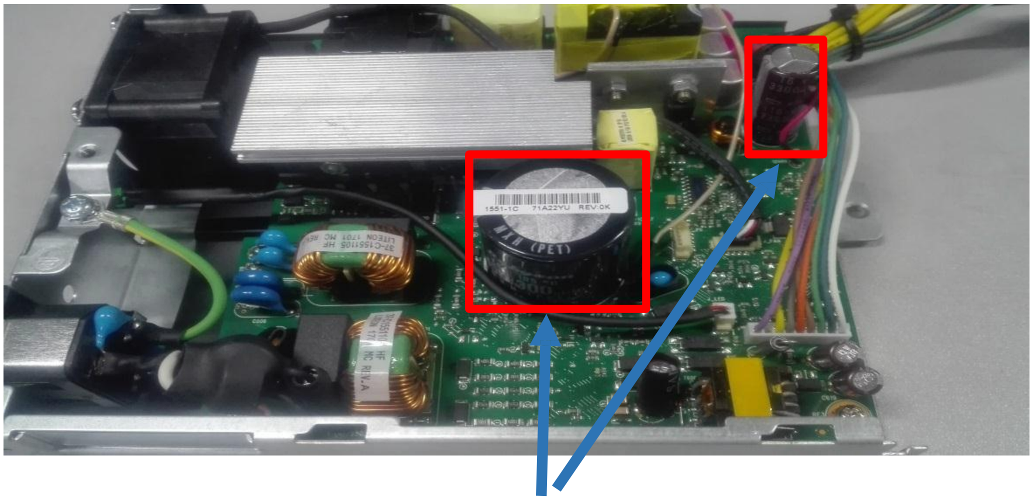
Attachment 12# : HSTNS-PL62

Remove capacitor

Attachment 13# : HSTNS-PD41

Remove capacitor

Attachment 14# : HSTNS-PL64



Remove capacitor